

Field Device Integration (FDI®) - Part 5: FDI
Information Model



EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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Field Device Integration (FDI®) - Part 5: FDI Information Model
(IEC 62769-5:2023)

Intégration des appareils de terrain (FDI®) - Partie 5:
Modèle d'Information FDI
(IEC 62769-5:2023)

Feldgeräteintegration (FDI®) - Teil 5: FDI-
Informationsmodell
(IEC 62769-5:2023)

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European foreword

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 5: FDI Information Model**

**Intégration des appareils de terrain (FDI®) –
Partie 5: Modèle d'Information FDI**



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 5: FDI Information Model**

**Intégration des appareils de terrain (FDI®) –
Partie 5: Modèle d'Information FDI**

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FIELD DEVICE INTEGRATION (FDI®) –

Part 5: FDI® Information Model

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IEC 62769-5 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added INTERACTIVE_TRANSFER_TO_DEVICE ACTION.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/858/CDV	65E/915/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 5: FDI® Information Model

1 Scope

This part of IEC 62769 defines the FDI®¹ Information Model. One of the main tasks of the Information Model is to reflect the topology of the automation system. Therefore, it represents the devices of the automation system as well as the connecting communication networks including their properties, relationships, and the operations that can be performed on them. The types in the AddressSpace of the FDI® Server constitute some kind of catalogue, which is built from FDI® Packages.

The fundamental types for the FDI® Information Model are well defined in OPC UA for Devices (IEC 62541-100). The FDI® Information Model specifies extensions for a few special cases and otherwise explains how these types are used and how the contents are built from elements of DevicePackages.

The overall FDI® architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration.

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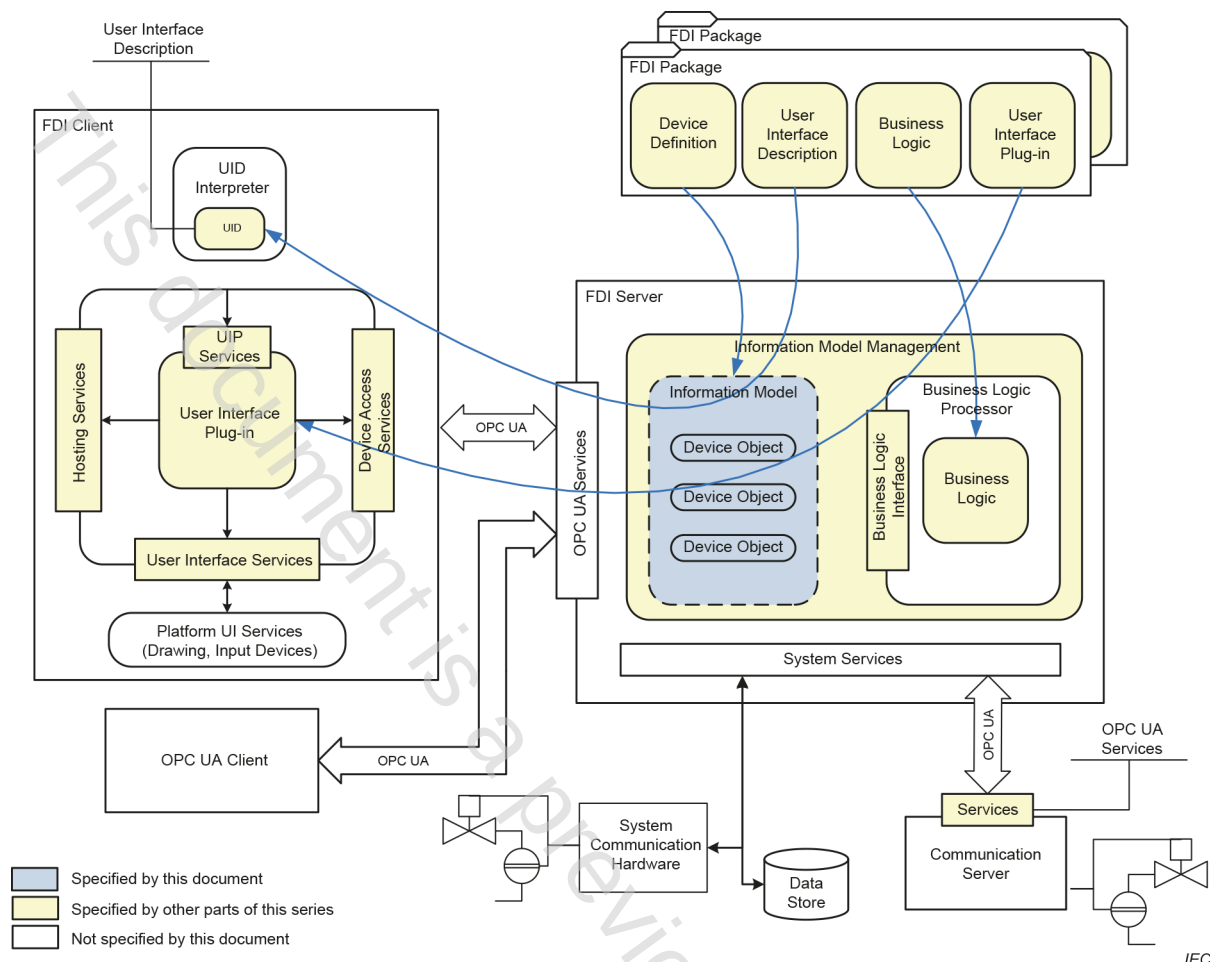


Figure 1 – FDI® architecture diagram

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1-3:2023, *Industrial networks – Profiles – Part 1-3: Fieldbus profiles – Communication Profile Family 3*

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-6, *OPC Unified Architecture – Part 6: Mappings*

IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

IEC 62769-3, *Field Device Integration (FDI®) – Part 3: Server*

IEC 62769-4, *Field Device Integration (FDI®) – Part 4: FDI® Packages*

IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

3 Terms, definitions, abbreviated terms, acronyms and conventions

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1 and IEC 62769-3 apply.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.2 Abbreviated terms and acronyms

For the purposes of this document, the abbreviated terms and acronyms given in IEC 62769-1 and the following apply.

HMI	Human Machine Interface
SCADA	Supervisory Control and Data Acquisition
TCP	Transmission Control Protocol

3.3 Conventions

3.3.1 Capitalization

Capitalization of the first letter of words is used in the IEC 62769 series to emphasize an FDI® defined term.

3.3.2 Conventions for graphical notation

OPC UA defines a graphical notation for an OPC UA AddressSpace. It defines graphical symbols for all NodeClasses and how different types of References between Nodes can be visualized. Figure 2 shows the symbols for the NodeClasses used in this document. NodeClasses representing types always have a shadow.